



# Material Composition Declaration

## EPC21701

Company Name	Efficient Power Conversion (EPC)	Issue Date:	8/15/2022
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	2.1 mg	Type of Product:	eGaN IC

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	1.8179	85.2356	87.9723	852356
	Silicon oxide	7631-86-9	0.0066	0.3105		3105
	Silicon nitride	12033-89-5	0.0024	0.1118		1118
	Gallium nitride	25617-97-4	0.0117	0.5465		5465
	Aluminum	7429-90-5	0.0142	0.6678		6678
	Aluminum nitride	24304-00-5	0.0028	0.1312		1312
	Titanium	7440-32-6	0.0005	0.0228		228
	Titanium nitride	25583-20-4	0.0021	0.0984		984
	Copper	7440-50-8	0.0002	0.0111		111
	Tungsten	7440-33-7	0.0031	0.1464		1464
	Polyimide		0.0147	0.6902	6902	
Under Bump Metal	Titanium	7440-32-6	0.0002	0.0082	0.0899	82
	Copper	7440-50-8	0.0017	0.0817		817
Solder Bump	Copper	7440-50-8	0.0174	0.8170	11.9378	8170
	Nickel	7440-02-0	0.0104	0.4874		4874
	Tin	7440-31-5	0.2227	10.4420		104420
	Silver	7440-22-4	0.0041	0.1914		1914
Sum in total:			2.1328	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.